EVG NIL Technology Day 2023 – November 23, 2023

Will 3D Heterogeneous System Integration Help Scale the ESG Wall?

At SEMICON Europa 2023, we heard more good news about 3D heterogeneous Integration from speakers at the CEO Summit and the Advanced Packaging Conference. Not only has it become the champion for the continuation of Moore's Law scaling, but it also allows us to deliver on power performance area and cost (PPAC) in a more environmentally friendly way. TSMC's Doug Yu calls it scaling the "ESG Wall". Imec's Emily Gallagher called it achieving PPAC-E.

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Getting Every Semiconductor Company to Net Zero

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IFTLE 576: TSMC Launches 3DFabric Alliance at OIP 2023

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SEMICON Europa 2023 In Review

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Keynote Conversations from SEMICON Europa 2023: Shaping a Sustainable $1T Era

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Community News

ACM Research Celebrates Opening of New Oregon Facility, Contributing to the Pacific Northwest's Growing Semiconductor Industry

Events Calendar

EVG NIL Technology Day 2023
November 29, 2023

25th IEEE Electronics Packaging Technology Conference
December 5-8, 2023

69th Annual IEEE International Electron Devices Meeting
December 9-13, 2023

SEMICON Japan 2023
December 13-15, 2023

Recommended Reads

CHIPS for America Releases Vision for Approximately $3 Billion National Advanced Packaging Manufacturing Program – Semiconductor Digest

Semiconductors Headed Toward Strong 2024 – SemiWiki.com

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